

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application:

**Listing of Claims:**

**Claim 1 (currently amended):** A sensor having a transistor with a gate located partially over a source and partially over a drain, comprising:

a well region formed beneath the source such that a portion of the well region extends partially beneath the gate, the well region having a first conductivity type;

a material disposed between the well region and the drain beneath the gate, the material having a predetermined length;

an implant in the material, the implant having said first conductivity type; and

a detection device coupled to the drain by a signal path, wherein the material allows the detection device to be reset to a predetermined state.

**Claim 2 (currently amended):** The sensor of claim 1, ~~further including an~~ wherein the implant in the material that increases a surface threshold of the transistor.

**Claim 3 (original):** The sensor of claim 2, wherein the surface threshold of the transistor is increased to at least 0.8 volts.

**Claim 4 (previously presented):** The sensor of claim 2, wherein the implant is formed to extend between the well region and the drain.

**Claim 5 (previously presented):** The sensor of claim 3, wherein the implant has a dopant concentration that is less than the well region.

**Claim 6 (previously presented):** The sensor of claim 2, wherein the implant is a shallow boron implant.

**Claim 7 (original):** The sensor of claim 2, wherein the predetermined length of the material is at least 20 percent greater than a process minimum.

**Claim 8 (original):** The sensor of claim 2, wherein the drain is formed by a phosphorous implant level between  $3e^{13} \text{ cm}^{-3}$  and about  $6e^{12} \text{ cm}^{-3}$ .

**Claim 9 (original):** The sensor of claim 2, wherein the gate has a gate length approximately two times a process minimum.

**Claim 10 (original):** The sensor of claim 1, wherein the gate is divided into a p-type region and a n-type region.

**Claim 11 (previously presented):** The sensor of claim 10, wherein the gate has a predetermined length that is approximately two times a process minimum.

**Claim 12 (original):** The sensor of claim 10, wherein the material is a p-type material.

**Claim 13 (previously presented):** The sensor of claim 12, wherein the material corresponds to a portion of a p-type substrate that is in proximity to the p-type region of the gate and the portion of the well region extends beneath the n-type region of the gate.

**Claim 14 (original):** The sensor of claim 10, wherein the drain is formed by a phosphorous implant level of approximately  $2e^{12} \text{ cm}^{-3}$ .

**Claim 15 (previously presented):** The sensor of claim 10, including an implant region located in the drain extending under the p-type region of the gate such that the drain is not in direct contact with the gate.

**Claim 16 (original):** The sensor of claim 15, wherein the implant region is a surface boron implant region.

**Claim 17 (original):** The sensor of claim 1, wherein the detection device is a photo-detector.

**Claim 18 (original):** The sensor of claim 17, wherein the photo-detector is a photodiode.

**Claim 50 (currently amended):** A sensor having a transistor with a gate located partially over a source and partially over a drain formed in a substrate, comprising:

a well region formed to contain one of the source and the drain such that a portion of the well region extends partially beneath the gate, the well region having a first conductivity type;

an implant formed in the substrate to extend between the well region and the other of the source and the drain such that the implant increases a surface threshold of the transistor, the implant having said first conductivity type; and

a detection device coupled to the drain by a signal path, wherein the implant allows the detection device to be reset to a predetermined state when a voltage that is greater than or equal to the surface threshold of the transistor is present on the gate.

**Claim 51 (previously presented):** The sensor of claim 50, wherein the surface threshold of the transistor is increased to at least 0.8 volts.

**Claim 52 (previously presented):** The sensor of claim 50, wherein the gate has a predetermined length and the implant extends approximately a half of the predetermined length of the gate.

**Claim 53 (previously presented):** The sensor of claim 52, wherein the predetermined length of the gate is at least 20 percent greater than a process minimum.

**Claim 54 (previously presented):** The sensor of claim 52, wherein the predetermined length of the gate is approximately two times a process minimum.

**Claim 55 (previously presented):** A sensor, comprising:

- a transistor having a source, a drain, and a gate located partially over the source and partially over the drain, the gate having a p-type region and a n-type region;
- a well region formed to contain one of the source and the drain and to extend partially beneath the gate such that the well region extends a length of one of the n-type and the p-type gate regions; and
- a detection device coupled to the drain by a signal path.

**Claim 56 (previously presented):** The sensor of claim 55, wherein the gate has a predetermined length that is approximately two times a process minimum.

**Claim 57 (previously presented):** The sensor of claim 55, wherein the well region is a p-type material and the well region extends the length of the n-type gate region.

**Claim 58 (previously presented):** The sensor of claim 57, further comprising an implant region located in the drain extending under the p-type region of the gate such that the drain is not in direct contact with the gate.

**Claim 59 (previously presented):** A sensor, comprising:

- a transistor having a source, a drain, and a gate located partially over the source and partially over the drain, the gate having a p-type gate region and an n-type gate region;
- a well region formed to contain one of the source and the drain and to extend partially beneath the gate, wherein the well region is a p-type material and the well region extends a length of the n-type gate region; and
- a detection device coupled to the drain by a signal path.

**Claim 60 (previously presented):** The sensor of claim 59, further comprising an implant region located in the drain extending under the p-type region of the gate such that the drain is not in direct contact with the gate.